

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application

1           1.   (Original) An IC card comprising:

2           (a) a wiring substrate having an external connecting  
3 terminal and wiring;

4           (b) a semiconductor chip disposed over the wiring  
5 substrate and connected electrically to the external  
6 connecting terminal through the wiring; and

7           (c) a case which covers the wiring substrate and the  
8 semiconductor chip in such a manner that the external  
9 connecting terminal of the wiring substrate is exposed,

10          wherein the case has a first end side near which the  
11 external connecting terminal is disposed and a second end  
12 side positioned on an opposite side to the first end side,  
13 and

14          wherein a planar outline of the wiring substrate is  
15 smaller than half of a planar outline of the case, and the  
16 wiring substrate is disposed in an area of the case closer  
17 to the first end side with respect to a middle position  
18 between the first and the second end side.

1           2.   (Original) An IC card according to claim 1,  
2   wherein the semiconductor chip is disposed in an area of  
3   the case closer to the first end side with respect to the  
4   middle position between the first and the second end side.

1           3.   (Original) An IC card according to claim 1,  
2   wherein the case comprises a first case and a second case,  
3   one of the first and the second case having a projecting  
4   portion in an area other than the area where the wiring  
5   substrate is disposed, the other case having a recess  
6   portion in an area other than the area where the wiring  
7   substrate is disposed, the projecting portion being fitted  
8   in the recess portion so as to connect the first and the  
9   second case with each other.

1           4.   (Original) An IC card according to claim 3,  
2   wherein a tip-side inner periphery portion of the recess  
3   portion and a tip-side outer periphery portion of the  
4   projecting portion are chamfered.

1           5.   (Original) An IC card according to claim 3,  
2   wherein the recess portion and the projecting portion have  
3   an aligning function for self-alignmentwise aligning planar

4 positions of the first and the second case when both said  
5 cases are superimposed one over the other.

1        6. (Original) An IC card according to claim 3,  
2 wherein the projecting portion formed over the first or the  
3 second case has a function for fixing the case formed with  
4 the projecting portion to a carrier temporarily.

1        7. (Original) An IC card according to claim 1,  
2 further comprising a movable switch,  
3 wherein the case comprises a first case and a second  
4 case, and in the first or the second case, a mechanism for  
5 holding the movable switch is provided in an area other  
6 than the area where the wiring substrate is disposed.

1        8. (Original) An IC card according to claim 1,  
2 further comprising a movable switch, wherein the case  
3 comprises a first case and a second case, and in the first  
4 or the second case, a click mechanism for the movable  
5 switch is provided in an area other than the area where the  
6 wiring substrate is disposed.

1           9. (Original) An IC card according to claim 1,  
2 further comprising a movable switch,  
3           wherein the case comprises a first case and a second  
4 case, and means for fixing the first and the second case to  
5 a carrier temporarily are provided in areas of the first  
6 and the second case other than the area where the wiring  
7 substrate is disposed.

1           10. (Original) An IC card comprising:

2           (a) a wiring substrate having an external connecting  
3 terminal and wiring;

4           (b) a semiconductor chip disposed over the wiring  
5 substrate and connected electrically to the external  
6 connecting terminal through the wiring; and

7           (c) a case which covers the wiring substrate and the  
8 semiconductor chip in such a manner that the external  
9 connecting terminal of the wiring substrate is exposed,

10          wherein a planar outline of the wiring substrate is  
11 smaller than half of a planar outline of the case, and

12          wherein the case comprises:

13          a first end side near which the external connecting  
14 terminal is disposed;

15           a second end side positioned on an opposite side to  
16 the first end side;  
17           a first area closer to the first end side with respect  
18 to a middle position between the first and the second end  
19 side, with the wiring substrate being disposed in the first  
20 area; and  
21           an insulating, second area positioned between the  
22 first area and the second end side.

1           11. (Original) An IC card comprising:  
2           (a) a wiring substrate having a plurality of external  
3 connecting terminals and wiring;  
4           (b) a semiconductor chip disposed over the wiring  
5 substrate and connected electrically to the external  
6 connecting terminals through the wiring; and  
7           (c) a case having an opening into which some of the  
8 plural external connecting terminals are exposed, the case  
9 covering the wiring substrate and the semiconductor chip  
10 and further covering some of the other external connecting  
11 terminals.

1           12. (Original) An IC card according to claim 11,  
2           wherein the case has a first end side near which the  
3           external connecting terminals are disposed and a second end  
4           side positioned on an opposite side to the first end side,  
5           and  
6           wherein a planar outline of the wiring substrate is  
7           smaller than half of a planar outline of the case, and the  
8           wiring substrate is disposed in an area of the case closer  
9           to the first end side with respect to a middle position  
10          between the first and the second end side.

13-20 (Cancelled)